



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



DRAM DDR2

RDIMM

RDIMM

UDIMM

SODIMM

mini DIMM



DDR2 has been the standard memory solutions for applications in virtually all market segments from Servers, PCs and Notebooks to Printers, Networking and Storage systems and many more for several years providing superior cost and performance criteria. DDR2 has started to relinquish its role as the memory industry's mainstream technology to DDR3 and is forecasted to become a legacy product by early 2011

Available in power supply voltages of 1.8V (and 1.55V for FB DIMMs) and with transfer data rates from 400Mb/s to 800Mb/s and beyond, DDR2 has been designed in a wide range of applications providing designers with numerous module options to choose from. Wintec offers a wide range of DDR2 Module solutions. Please click on the link to find out more about our solutions.

[more images](#)

DDR2 - 240-Pin DIMM - Registered ECC

Standard Profile (1.181") with Nominal Voltage (1.8V)

Density	Part Number	Rank	DIMM Config	Component Config	Voltage
1GB	WD2RE01GX809-xxxx-yyz	1 rank	128x72	128Mx8	1.8V
	WD2RE01GX418-xxxx-yyz	1 rank	128x72	128Mx4	1.8V
2GB	WD2RE02GX818-xxxx-yyz	2 rank	256x72	128Mx8	1.8V
	WD2RE04GX418-xxxx-yyz	1 rank	512x72	512Mx4	1.8V
4GB	WD2RE04GX436-xxxx-yyz	2 rank	512x72	256Mx4	1.8V
	WD2RE04GX836-xxxx-yyz	4 rank	512x72	128Mx8	1.8V
8GB	WD2RE08GX436-xxxx-yyz	2 rank	1024x72	512Mx4	1.8V
	WD2RE08GX836-xxxx-yyz	4 rank	1024x72	256Mx8	1.8V

Very Low Profile (0.72") with Nominal Voltage (1.8V)

Density	Part Number	Rank	DIMM Config	Component Config	Voltage
1GB	WD2RE01GX809V-xxxx-yyz	1 rank	128x72	128Mx8	1.8V
	WD2RE01GX418V-xxxx-yyz	1 rank	128x72	128Mx4	1.8V
2GB	WD2RE02GX818V-xxxx-yyz	2 rank	256x72	128Mx8	1.8V
	WD2RE04GX418V-xxxx-yyz	1 rank	512x72	512Mx4	1.8V
4GB	WD2RE04GX818V-xxxx-yyz	2 rank	512x72	256Mx8	1.8V
	WD2RE08GX818V-xxxx-yyz	2 rank	1024x72	512Mx8	1.8V

(xxxx) Modules Speed (MHz) and CAS Latency

= 800I : 800MHz CL6
 800G : 800MHz CL5
 667G : 667MHz CL5
 533E : 533MHz CL4

DRAM Manufacturer and Die Revision

(yy) = P: Samsung A: A-Die
 H: Micron B: B-Die
 C: Hynix C: C-Die

Buffer / Register set (Only applies to Registered/Buffered modules)

(z) = I: Inphi

D: IDT
L: Intel